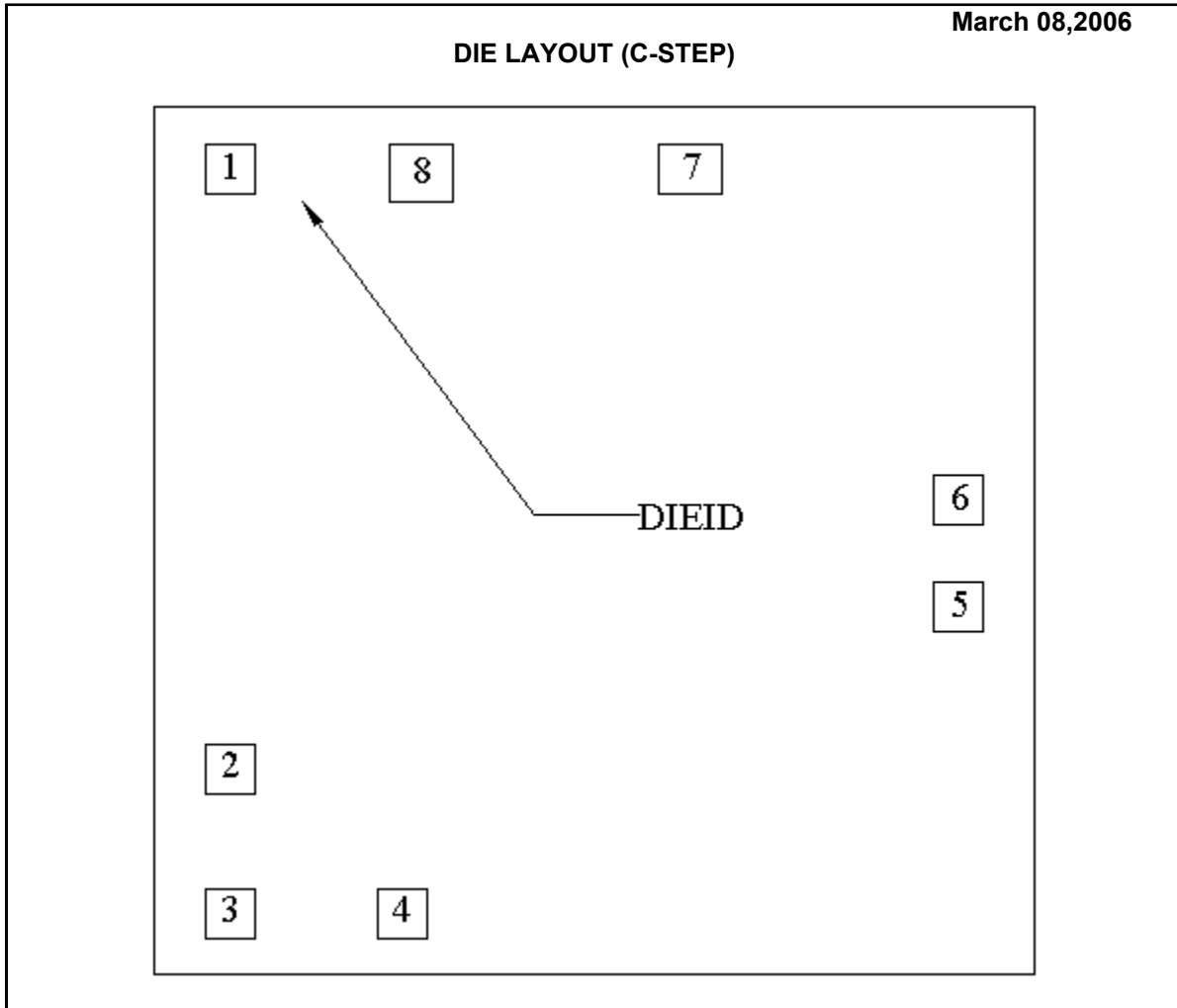


**LM567C MDC MWC  
TONE DECODER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM567C	Bond Pad Opening Size (min)	91μm x 91μm
Die Step	C	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1600μm x 1626μm 63.0mils x 64.0mils	Back Side Connection	Floating
Thickness	406μm Nominal		
Min Pitch	198μm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) <b>NC</b> = No Connection, <b>N.U.</b> = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT FILTER	1	-673	686	91	x	91
LOOP FILTER	2	-673	-419	91	x	91
INPUT	3	-673	-686	91	x	91
V+	4	-356	-686	91	x	91
TIMING RES	5	673	-122	91	x	91
TIMING CAP	6	673	76	91	x	91
GND	7	178	686	117	x	91
OUTPUT	8	-318	679	117	x	104

**LM567C MDC MWC**  
**tone DECODER**

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